



Batam

KEY SERVICES

- Wafer probe
- Wafer Backgrinding
- Assembly of Leadframe, Array and Leadless packages
- Final Test
- Tape and Reel
- Drop Shipping and Distribution

KEY FACTS

- Factory Floor Space Services: 409,000 ft² (38,000 m²)
- Equipment Capacity: 5 million units/capacity a day
- Employees: 1,500

SUPPLIER AWARDS

- On Semi, Freescale, EXAR, Delphi, Elmos, Infineon, Zilog, IDT, Zarlink

TEST PLATFORMS

- Linear/Analog
- High-end RF
- Mixed Signal
- VLSI

PACKAGE PORTFOLIO

- Array Packages - FBGA, LGA
- Leadframe Packages - TSSOP, SSOP, QSOP, QFP, LQFP, TQFP, PLCC, SOIC, PDIP
- Leadless Packages - DFN/QFN
- MEMS Packaging

CERTIFICATIONS

- ISO 14001:2004
- ISO 9001:2008
- ISO/TS 16949:2009
- Certificate of Green Partner (Sony)

